



Product Change Notification

CN-202411030F

Issue date: 06 Dec 2024

Effective date: 20 Mar 2025

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Change of wire diameter in package SOT457 for product PESD24VS5UD-Q

Change Category

<input type="checkbox"/> Wafer	<input checked="" type="checkbox"/> Assembly			
Fab	Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer	<input checked="" type="checkbox"/> Assembly	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
Fab	Materials			<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Wafer	<input type="checkbox"/> Assembly	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	
Fab	Location			

Details of this change

The wire diameter for product PESD24VS5UD-Q will be changed from 50µm to 22.5µm. The wire material Au remains unchanged. The wire bond process with 22.5µm Au is already released and in production at the assembly site Nexperia ATSN. No change in other package related parameters like die attach, wire routing, mold compound. Die design and active area remain unchanged.

CN-202411030FPCN-FORM-Rev_5_0_2.xlsm:

https://qcm.nexperia.com/Document/DOC-585562/CN-202411030FPCN-FORM-Rev_5_0_2.xlsm

CN-202411030F_changeMatrix.xlsx:

https://qcm.nexperia.com/Document/DOC-585483/CN-202411030F_changeMatrix.xlsx

SQRCN-202411030FNexperia.pdf:

<https://qcm.nexperia.com/Document/DOC-585480/SQRCN-202411030FNexperia.pdf>

CN-202411030FDeQuMaZVEI-5_0_14.xlsm:

https://qcm.nexperia.com/Document/DOC-585481/CN-202411030FDeQuMaZVEI-5_0_14.xlsm

Chem_Content_PESD24VS5UD-Q-CN-202411030F_20241128.pdf:

https://qcm.nexperia.com/Document/DOC-585325/Chem_Content_PESD24VS5UD-Q-CN-202411030F_20241128.pdf

Why do we implement this change?

Wire bond material will be adapted for standardization reasons. This contributes to the continuous optimization and harmonization of our production.

Identification of affected products

Changed products can be identified by date code after implementation.

Product availability

Production

Planned first shipment: 20 Mar 2025

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 05 Jan 2025. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

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